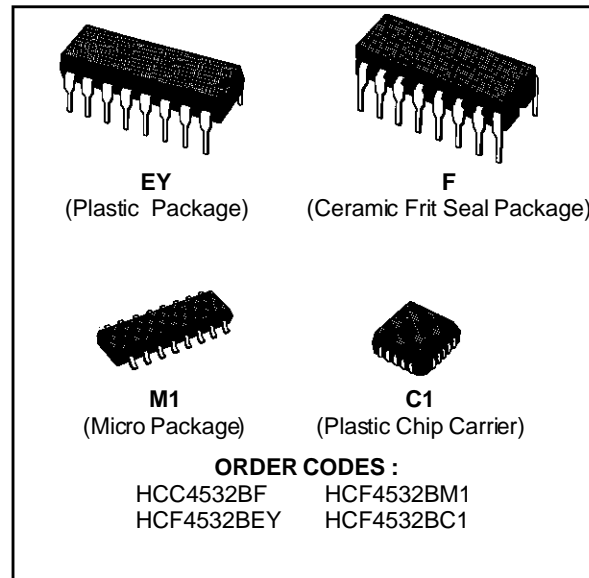


8-BIT PRIORITY ENCODER

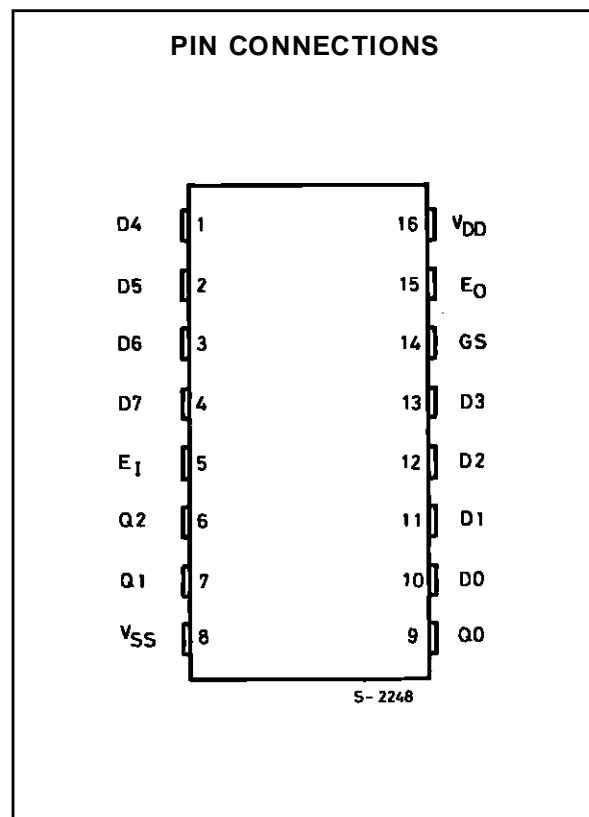
- CONVERTS FROM 1 OF 8 TO BINARY
- PROVIDES CASCADING FEATURE TO HANDLE ANY NUMBER OF INPUTS
- GROUP SELECT INDICATES ONE OR MORE PRIORITY INPUTS
- QUIESCENT CURRENT SPECIFIED TO 20V FOR HCC DEVICE
- STANDARDIZED SYMMETRICAL OUTPUT CHARACTERISTICS
- 5V, 10V, AND 15V PARAMETRIC RATINGS
- INPUT CURRENT OF 100 nA AT 18V AND 25°C FOR HCC DEVICE
- 100% TESTED FOR QUIESCENT CURRENT
- MEETS ALL REQUIREMENTS OF JEDEC TENTATIVE STANDARD N° 13A, "STANDARD SPECIFICATIONS FOR DESCRIPTION OF "B" SERIES CMOS DEVICES"



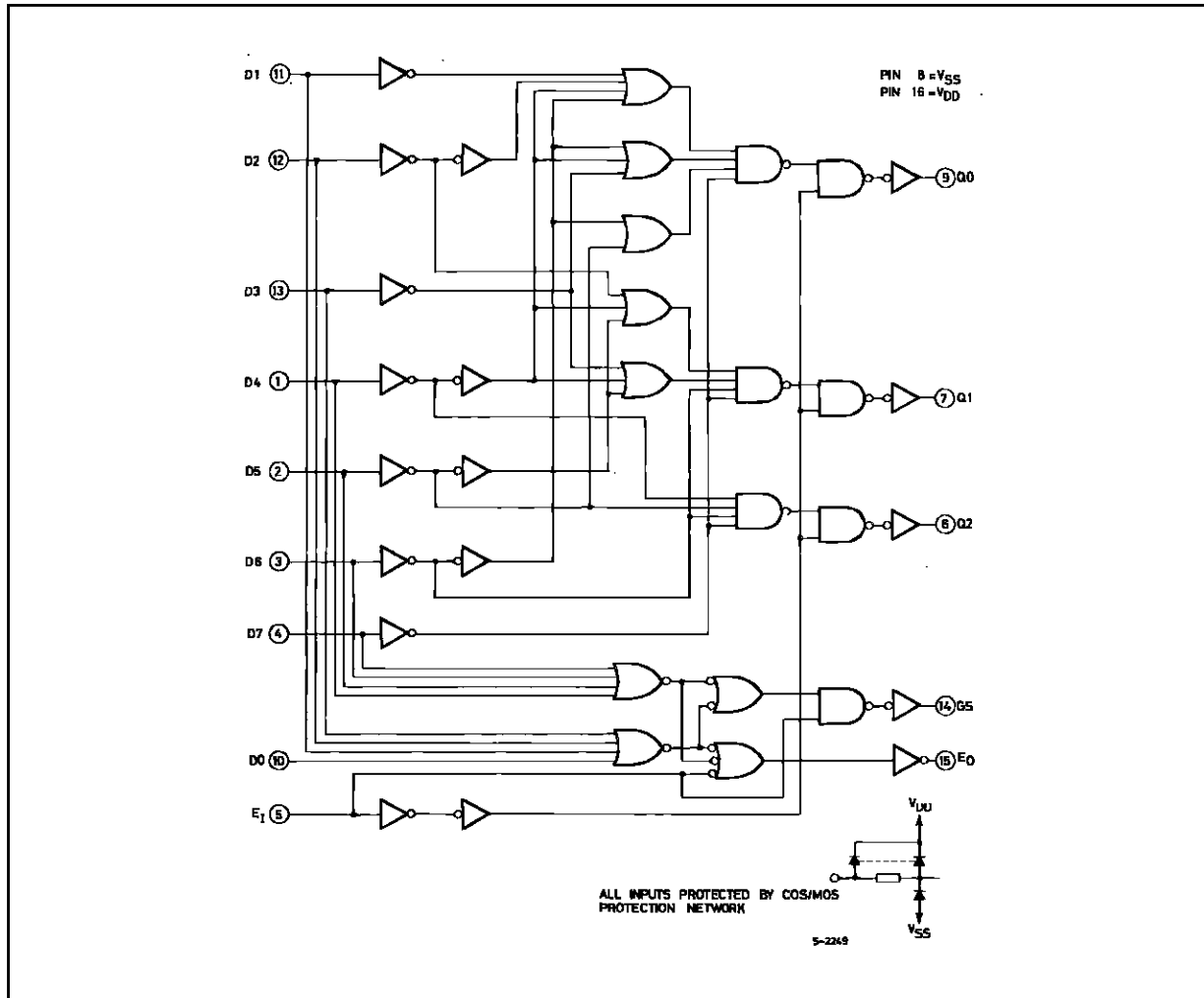
DESCRIPTION

The **HCC4532B** (extended temperature range) and **HCF4532B** (intermediate temperature range) are monolithic integrated circuit, available in 16-lead dual in-line plastic or ceramic package and plastic micro package.

The **HCC/HCF4532** consists of combinational logic that encodes the highest priority input (D7-D0) to a 3-bit binary code. The eight inputs, D7 through D0, each have an assigned priority. D7 is the highest priority and D0 is the lowest. The priority encoder is inhibited when the chip-enable input E_i is low. When E_i is high, the binary representation of the highest-priority input appears on output lines Q2-Q0, and the group select line GS is high to indicate that priority inputs are present. The enable-out (E_o) is high when no priority inputs are present. If any one input is high, E_o is low and all cascaded lower-order stages are disabled.



LOGIC DIAGRAM



TRUTH TABLE

Input									Output				
E ₁	D7	D6	D5	D4	D3	D2	D1	D0	GS	Q2	Q1	Q0	E _o
0	X	X	X	X	X	X	X	X	0	0	0	0	0
1	0	0	0	0	0	0	0	0	0	0	0	0	1
1	1	X	X	X	X	X	X	X	1	1	1	0	0
1	0	1	X	X	X	X	X	X	1	1	1	1	0
1	0	0	1	X	X	X	X	X	1	1	0	0	0
1	0	0	0	1	X	X	X	X	1	1	0	1	0
1	0	0	0	0	1	X	X	X	1	0	1	1	0
1	0	0	0	0	0	1	X	X	1	0	1	0	0
1	0	0	0	0	0	0	1	X	1	0	0	1	0
1	0	0	0	0	0	0	0	1	1	0	0	0	0

X ≡ Don't Care

Logic 1 ≡ High

Logic 0 ≡ Low

HCC/HCF4532B

STATIC ELECTRICAL CHARACTERISTICS (over recommended operating conditions)

Symbol	Parameter		Test Conditions				Value						Unit	
			V _I (V)	V _O (V)	I _O (μ A)	V _{DD} (V)	T _{Low} *		25°C			T _{High} *		
							Min.	Max.	Min.	Typ.	Max.	Min.		Max.
I _L	Quiescent Current	HCC Types	0/ 5			5		5		0.04	5		150	μ A
			0/10			10		10		0.04	10		300	
			0/15			15		20		0.04	20		600	
			0/20			20		100		0.08	100		3000	
		HCF Types	0/ 5			5		20		0.04	20		150	
			0/10			10		40		0.04	40		300	
			0/15			15		80		0.04	80		600	
V _{OH}	Output High Voltage	0/ 5		< 1	5	4.95		4.95			4.95		V	
		0/10		< 1	10	9.95		9.95			9.95			
		0/15		< 1	15	14.95		14.95			14.95			
V _{OL}	Output Low Voltage	5/0		< 1	5		0.05			0.05		0.05	V	
		10/0		< 1	10		0.05			0.05		0.05		
		15/0		< 1	15		0.05			0.05		0.05		
V _{IH}	Input High Voltage		0.5/4.5	< 1	5	3.5		3.5			3.5		V	
			1/9	< 1	10	7		7			7			
			1.5/13.5	< 1	15	11		11			11			
V _{IL}	Input Low Voltage		4.5/0.5	< 1	5		1.5			1.5		1.5	V	
			9/1	< 1	10		3			3		3		
			13.5/1.5	< 1	15		4			4		4		
I _{OH}	Output Drive Current	HCC Types	0/ 5	2.5		5	- 2		- 1.6	- 3.2		- 1.15	mA	
			0/ 5	4.6		5	- 0.64		- 0.51	- 1		- 0.36		
			0/10	9.5		10	- 1.6		- 1.3	- 2.6		- 0.9		
			0/15	13.5		15	- 4.2		- 3.4	- 6.8		- 2.4		
		HCF Types	0/ 5	2.5		5	- 1.53		- 1.36	- 3.2		- 1.1		
			0/ 5	4.6		5	- 0.52		- 0.44	- 1		- 0.36		
			0/10	9.5		10	- 1.3		- 1.1	- 2.6		- 0.9		
	0/15	13.5		15	- 3.6		- 3.0	- 6.8		- 2.4				
I _{OL}	Output Sink Current	HCC Types	0/ 5	0.4		5	0.64		0.51	1		0.36	mA	
			0/10	0.5		10	1.6		1.3	2.6		0.9		
			0/15	1.5		15	4.2		3.4	6.8		2.4		
		HCF Types	0/ 5	0.4		5	0.52		0.44	1		0.36		
			0/10	0.5		10	1.3		1.1	2.6		0.9		
			0/15	1.5		15	3.6		3.0	6.8		2.4		
I _{IH} , I _{IL}	Input Leakage Current	HCC Types	0/18	Any Input		18		\pm 0.1		\pm 10 ⁻⁵	\pm 0.1		\pm 1	μ A
		HCF Types	0/15			15		\pm 0.3		\pm 10 ⁻⁵	\pm 0.3		\pm 1	
C _I	Input Capacitance		Any Input						5	7.5			pF	

* T_{Low} = - 55°C for HCC device : - 40°C for HCF device.

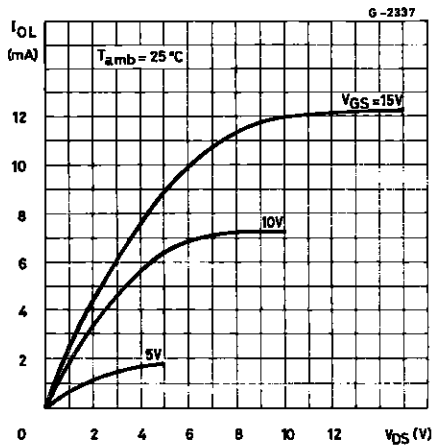
* T_{High} = + 125°C for HCC device : + 85°C for HCF device.

The Noise Margin for both "1" and "0" level is : 1V min. with V_{DD} = 5V, 2V min. with V_{DD} = 10V, 2.5 V min. with V_{DD} = 15V.

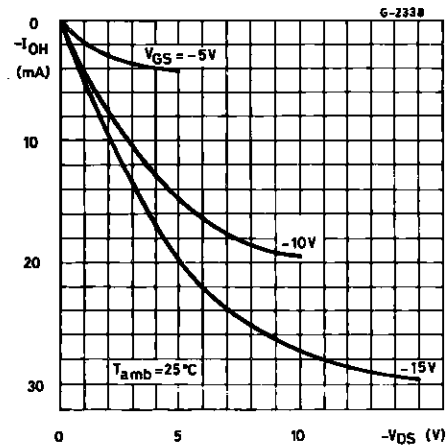
DYNAMIC ELECTRICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}\text{C}$, $C_L = 50\text{pF}$, $R_L = 200\text{k}\Omega$, typical temperature coefficient for all V_{DD} values is $0.3\%/^{\circ}\text{C}$, all input rise and fall times = 20ns)

Symbol	Parameter	Test Conditions		Value			Unit
			V_{DD} (V)	Min.	Typ.	Max.	
t_{PLH} , t_{PHL}	Propagation Delay Time (E_1 to E_O , E_1 to GS)		5		110	220	ns
			10		55	110	
			15		45	85	
t_{PLH} , t_{PHL}	Propagation Delay Time (E_1 to Q_m , D_n to GS)		5		170	340	ns
			10		85	170	
			15		65	125	
t_{PLH} , t_{PHL}	Propagation Delay Time (D_n to Q_M)		5		220	440	ns
			10		110	220	
			15		85	160	
t_{TLH} , t_{THL}	Transition Time		5		100	200	ns
			10		50	100	
			15		40	80	

Minimum Output Low (sink) Current Characteristics.

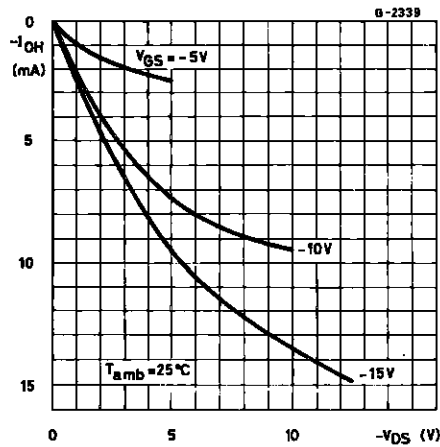


Typical Output High (source) Current Characteristics.

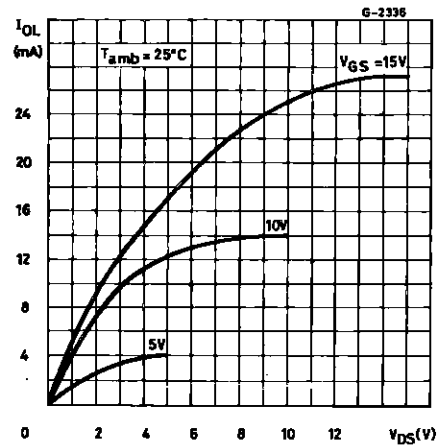


HCC/HCF4532B

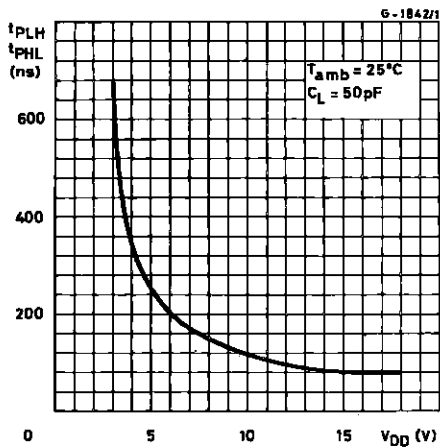
Minimum Output High (source) Current Characteristics.



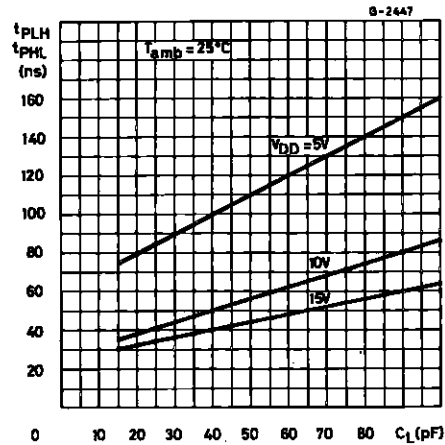
Typical Output Low (sink) Current Characteristics.



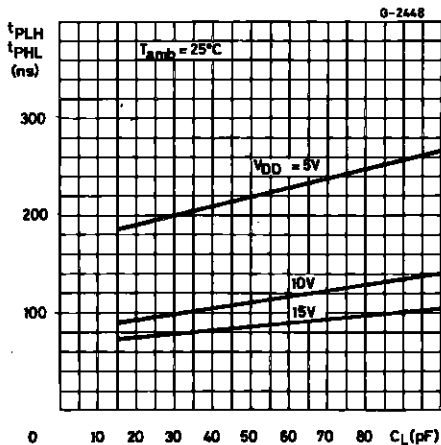
Typical Propagation Delay (Dn to Qm) vs. Supply Voltage.



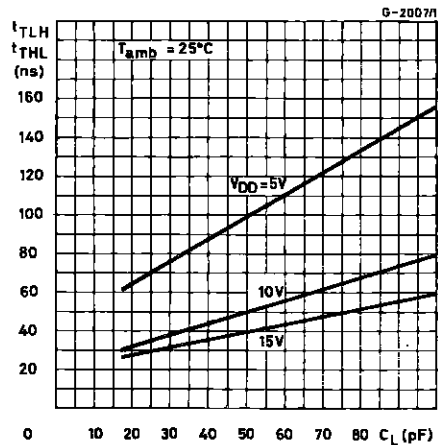
Typical Propagation Delay (E1 to GS, E1 to E0) vs. Load Capacitance.



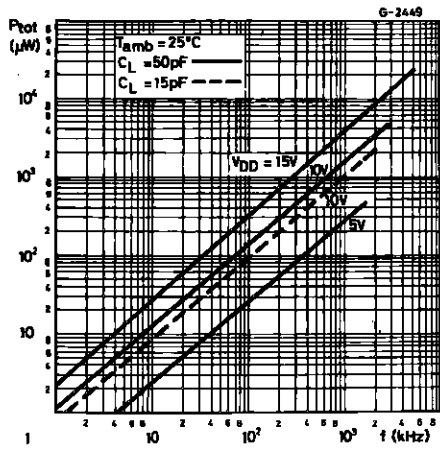
Typical Propagation Delay (Dn to Qm) vs. Load Capacitance.



Typical Transition Time vs. Load Capacitance.

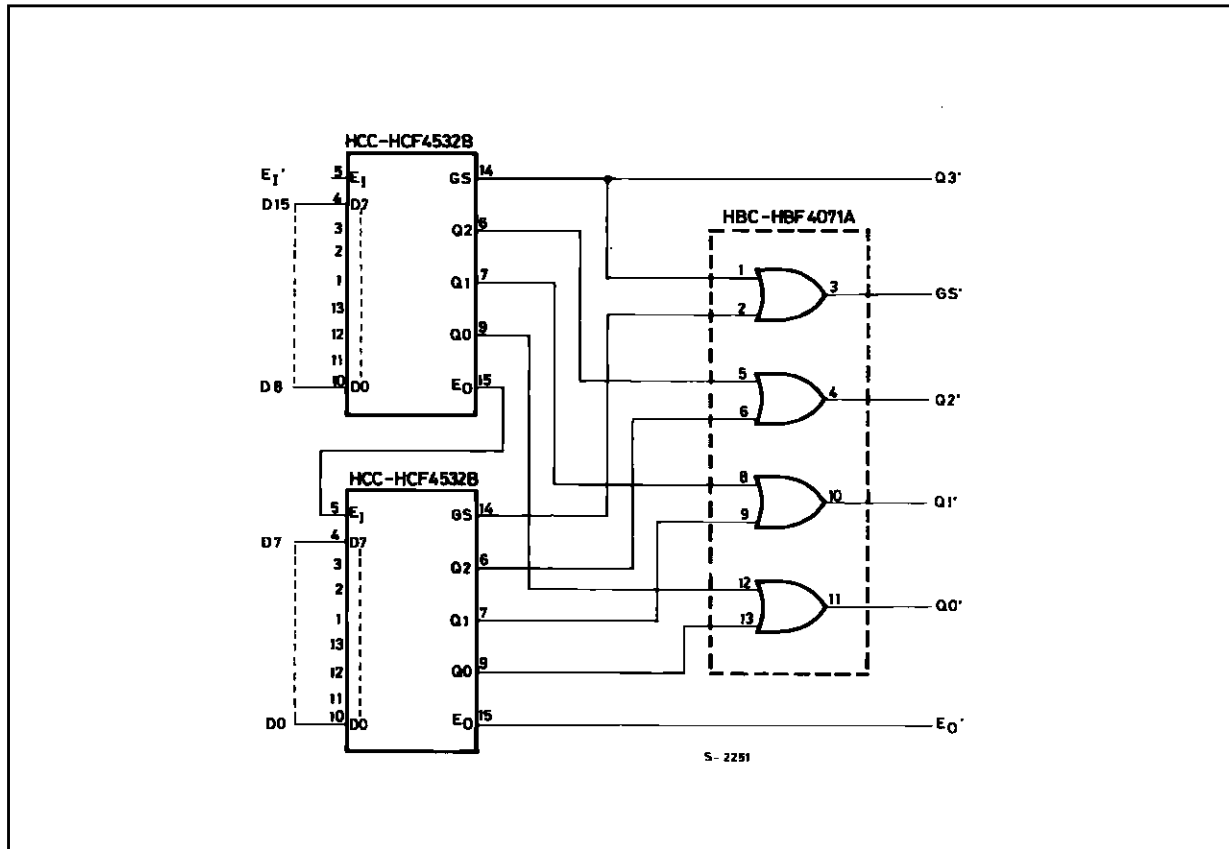


Typical Dynamic Power Dissipation vs. Frequency.



APPLICATIONS

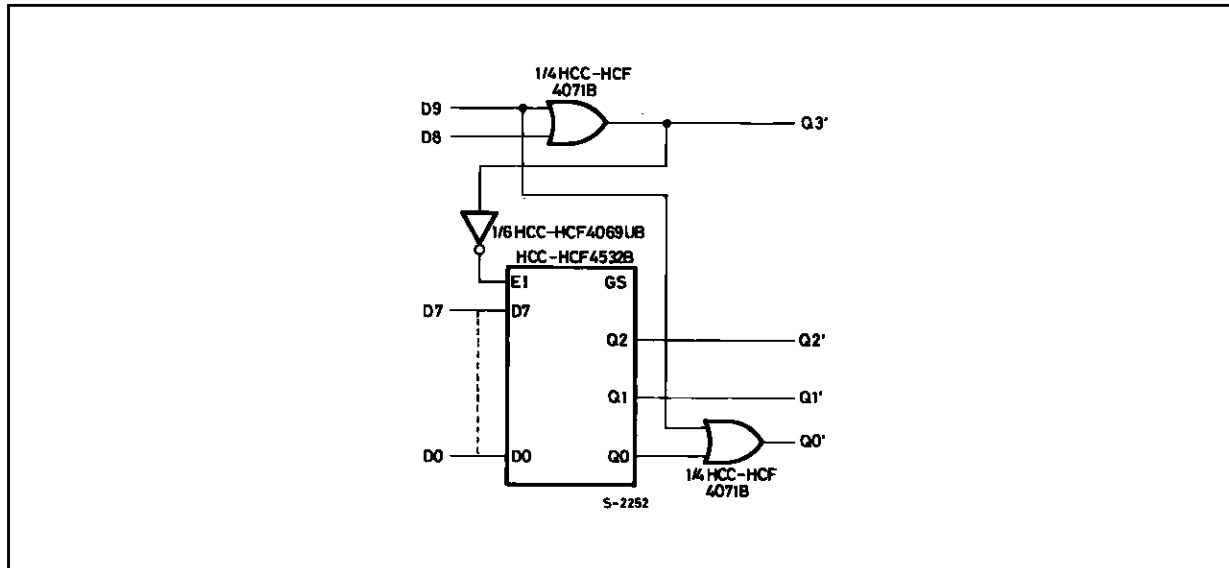
16-LEVEL PRIORITY ENCODER



HCC/HCF4532B

APPLICATIONS (continued)

0-TO-9 KEYBOARD ENCODER



TRUTH TABLE

Input										Output				
D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	GS	Q3'	Q2'	Q1'	Q0
1	X	X	X	X	X	X	X	X	X	0	1	0	0	1
0	1	X	X	X	X	X	X	X	X	0	1	0	0	0
0	0	1	X	X	X	X	X	X	X	1	0	1	1	1
0	0	0	1	X	X	X	X	X	X	1	0	1	1	0
0	0	0	0	1	X	X	X	X	X	1	0	1	0	1
0	0	0	0	0	1	X	X	X	X	1	0	1	0	0
0	0	0	0	0	0	1	X	X	X	1	0	0	1	1
0	0	0	0	0	0	0	1	X	X	1	0	0	1	0
0	0	0	0	0	0	0	0	1	X	1	0	0	0	1
0	0	0	0	0	0	0	0	0	1	1	0	0	0	0

X = Don't Care

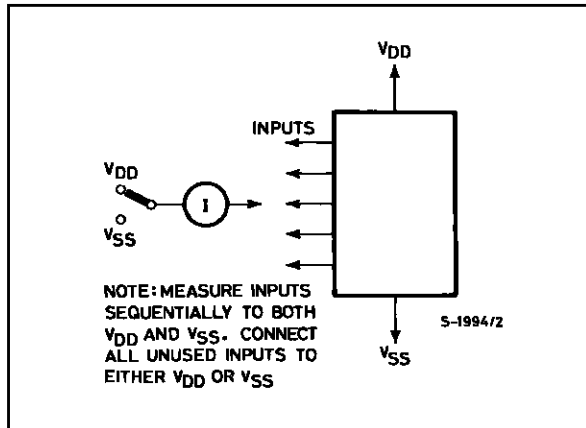
Logic 1 ≡ High

Logic 0 ≡ Low

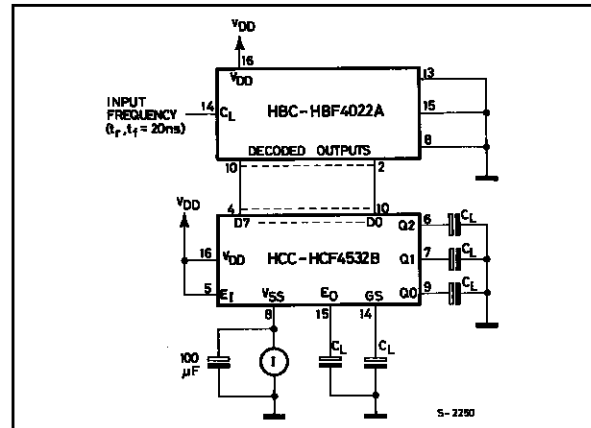
HCC/HCF4532B

TEST CIRCUITS (continued)

Quiescent Device Current.



Dynamic Power Dissipation.



Plastic DIP16 (0.25) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		17.78			0.700	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z			1.27			0.050



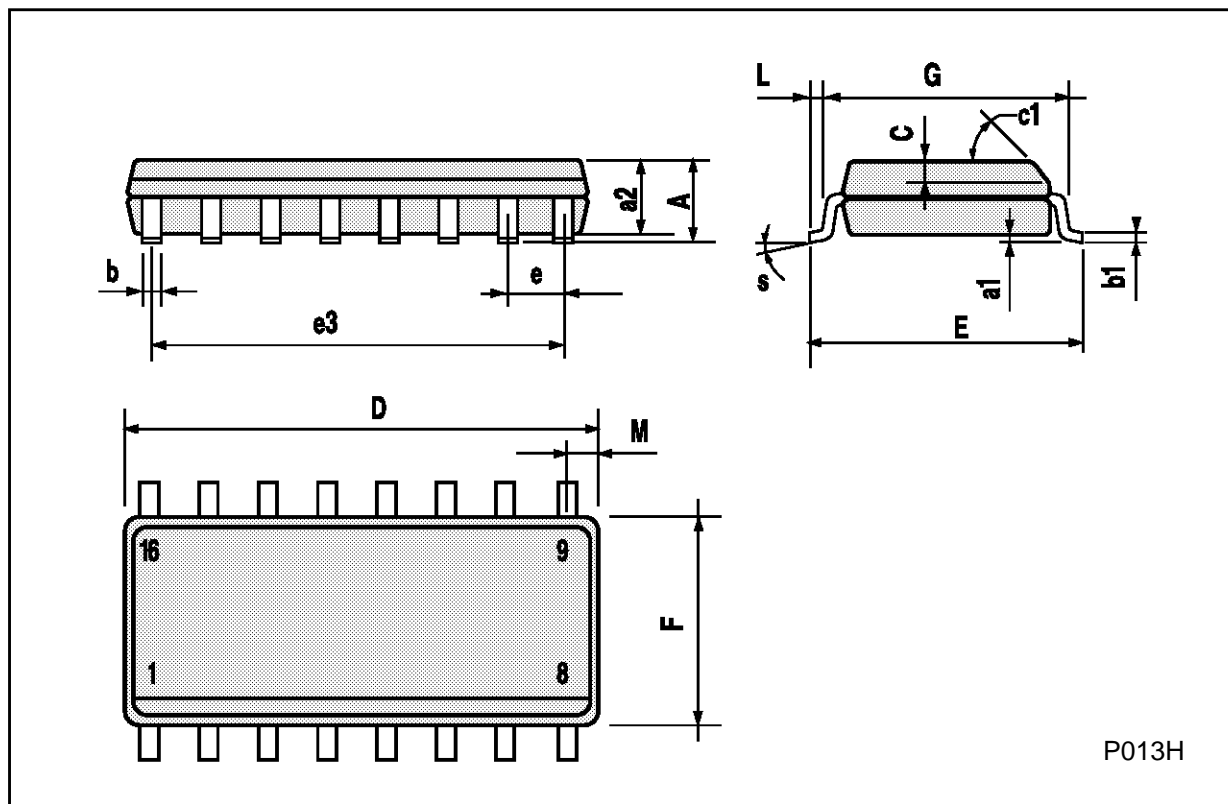
Ceramic DIP16/1 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			20			0.787
B			7			0.276
D		3.3			0.130	
E	0.38			0.015		
e3		17.78			0.700	
F	2.29		2.79	0.090		0.110
G	0.4		0.55	0.016		0.022
H	1.17		1.52	0.046		0.060
L	0.22		0.31	0.009		0.012
M	0.51		1.27	0.020		0.050
N			10.3			0.406
P	7.8		8.05	0.307		0.317
Q			5.08			0.200



SO16 (Narrow) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.2	0.004		0.007
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	9.8		10	0.385		0.393
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		8.89			0.350	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.62			0.024
S	8° (max.)					



P013H

PLCC20 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	9.78		10.03	0.385		0.395
B	8.89		9.04	0.350		0.356
D	4.2		4.57	0.165		0.180
d1		2.54			0.100	
d2		0.56			0.022	
E	7.37		8.38	0.290		0.330
e		1.27			0.050	
e3		5.08			0.200	
F		0.38			0.015	
G			0.101			0.004
M		1.27			0.050	
M1		1.14			0.045	



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